NTP5N60

Preferred Devices

Product Preview

Power MOSFET 5 Amps, 600 Volts

N−Channel TO−220

Designed for high voltage, high speed switching applications in power supplies, converters, power motor controls and bridge circuits.

Features

- Higher Current Rating
- Lower $R_{DS(on)}$
- Lower Capacitances
- Lower Total Gate Charge
- Tighter V_{SD} Specifications
- Avalanche Energy Specified

Typical Applications

- Switch Mode Power Supplies
- PWM Motor Controls
- Converters
- Bridge Circuits

MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Drain−Source Voltage	V_{DSS}	600	Vdc
Drain−Gate Voltage (R_{GS} = 1.0 MΩ)	V_{DGR}	600	Vdc
Gate−Source Voltage − Continuous − Non−Repetitive ($t_p \le 10$ ms)	 V_{GS} V_{GS}	 ±20 ±40	Vdc
Drain − Continuous @ T_A 25°C − Continuous @ T_A 100°C − Single Pulse ($t_p \le 10$ μs)	I_D I_D I_{DM}	5 3.8 17.5	Adc Apk
Total Power Dissipation @ T_A 25°C Derate above 25°C Total Power Dissipation @ T_A 25°C (Note 1.)	P_D	96 0.77 1.75	Watts W/°C Watts
Operating and Storage Temperature Range	T_J, T_{stg}	−55 to +150	°C
Single Drain−to−Source Avalanche Energy − Starting T_J = 25°C (V_{DD} = 100 V, V_{GS} = 10 Vdc, I_L(pk) = 5 A, L = 10 mH, V_{DS} = 600 Vdc, R_G = 25 Ω)	E_{AS}	80	mJ
Thermal Resistance − Junction−to−Case − Junction−to−Ambient	 $R_{\theta JC}$ $R_{\theta JA}$	 1.3 62.5	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8″ from case for 10 seconds	T_L	260	°C

1. Repetitive rating; pulse width limited by maximum junction temperature.

This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.

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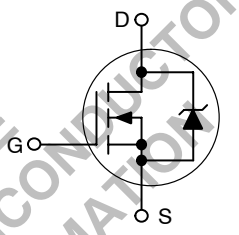
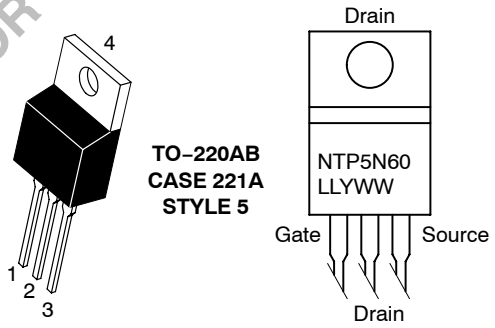
5 AMPERES
600 VOLTS
$R_{DS(on)}$ = 2400 mΩ

N−Channel



MARKING DIAGRAMS AND PIN ASSIGNMENTS



NTP5N60 = Device Code
LL = Location Code
Y = Year
WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
NTP5N60	TO−220AB	50 Units/Rail

Preferred devices are recommended choices for future use and best overall value.

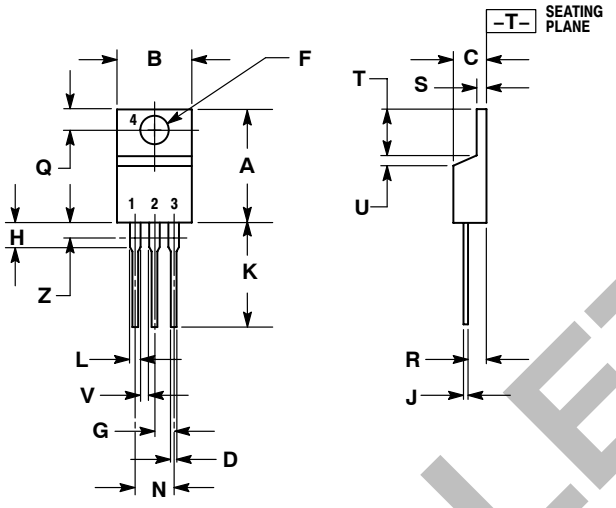
ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Drain−to−Source Breakdown Voltage (Note 1) (V_{GS} = 0 Vdc, I_D = 250 μAdc) Temperature Coefficient (Positive)	$V_{(BR)DSS}$	 600 –	 – 700	 – –	Vdc mV/°C
Zero Gate Voltage Drain Current (V_{DS} = 600 Vdc, V_{GS} = 0 Vdc) (V_{DS} = 600 Vdc, V_{GS} = 0 Vdc, T_J =125°C)	I_{DSS}	 – –	 – –	 10 100	μAdc
Gate−Body Leakage Current (V_{GS} = ±20 Vdc, V_{DS} = 0 Vdc)	I_{GSS}	–	–	±100	nAdc
ON CHARACTERISTICS (Note 1)					
Gate Threshold Voltage (V_{DS} = V_{GS}, I_D = 250 μAdc) Temperature Coefficient (Negative)	$V_{GS(th)}$	 2.0 –	 2.7 6.0	 4.0 –	Vdc mV/°C
Static Drain−to−Source On−Resistance (V_{GS} = 10 Vdc, I_D = 2.5 Adc)	$R_{DS(on)}$	–	2100	2400	mOhm
Static Drain−to−Source On−Resistance (V_{GS} = 10 Vdc, I_D = 5 Adc) (V_{GS} = 10 Vdc, I_D = 2.5 Adc, T_J = 125°C)	$V_{DS(on)}$	 – –	 – –	 14.4 13.1	V
Forward Transconductance (V_{DS} = 15 Vdc, I_D = 2.5 Adc)	g_{FS}	0.7	3.8	–	mhos
DYNAMIC CHARACTERISTICS					
Input Capacitance	(V_{DS} = 25 Vdc, V_{GS} = 0 Vdc, f = 1.0 MHz)	C_{iss}	–	540	780	pF
Output Capacitance		C_{oss}	–	125	180	
Transfer Capacitance		C_{rss}	–	8.0	20	
SWITCHING CHARACTERISTICS (Note 2)					
Turn−On Delay Time	(V_{DD} = 300 Vdc, I_D = 5 Adc, V_{GS} = 10 Vdc, R_G = 9.1 Ω)	$t_{d(on)}$	–	12	20	ns
Rise Time		t_r	–	7.0	10	
Turn−Off Delay Time		$t_{d(off)}$	–	19	40	
Fall Time		t_f	–	10	20	
Gate Charge	(V_{DS} = 400 Vdc, I_D = 5 Adc, V_{GS} = 10 Vdc)	Q_T	–	5.0	10	nC
		Q_1	–	2.7	–	
		Q_2	–	2.0	–	
SOURCE−DRAIN DIODE CHARACTERISTICS					
Forward On−Voltage (Note 1)	(I_S = 5 Adc, V_{GS} = 0 Vdc) (I_S = 5 Adc, V_{GS} = 0 Vdc, T_J = 125°C)	V_{SD}	 –	0.86 0.75	1.0 –	Vdc
Reverse Recovery Time	(I_S = 5 Adc, V_{GS} = 0 Vdc, di_S/dt = 100 A/μs)	t_{rr}	–	655	–	ns
		t_a	–	103	–	
		t_b	–	552	–	
Reverse Recovery Stored Charge		Q_{RR}	–	1.9	–	μC

1. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
2. Switching characteristics are independent of operating junction temperature.

PACKAGE DIMENSIONS

TO−220 THREE−LEAD
TO−220AB
CASE 221A−09
ISSUE AA



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.570	0.620	14.48	15.75
B	0.380	0.405	9.66	10.28
C	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
H	0.110	0.155	2.80	3.93
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045	---	1.15	---
Z	---	0.080	---	2.04

STYLE 5:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
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